PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT2716162

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
HIREN D. THACKER	10/07/2013
FRANKIE Y. LIU	10/07/2013
ROBERT DAVID HOPKINS II	10/07/2013
JON LEXAU	10/07/2013
XUEZHE ZHENG	10/07/2013
GUOLIANG LI	10/09/2013
IVAN SHUBIN	10/07/2013
RONALD HO	10/07/2013
JOHN E. CUNNINGHAM	10/07/2013
ASHOK V. KRISHNAMOORTHY	10/07/2013

RECEIVING PARTY DATA

Name:	ORACLE INTERNATIONAL CORPORATION
Street Address:	500 ORACLE PARKWAY
Internal Address:	MAIL STOP 5OP7
City:	REDWOOD CITY
State/Country:	CALIFORNIA
Postal Code:	94065

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14047910

CORRESPONDENCE DATA

Fax Number:	(530)759-1665
Phone:	530-759-1661
Email:	joanne@parklegal.com

Correspondence will be sent via US Mail when the email attempt is unsuccessful.

Correspondent Name:	A. RICHARD PARK

Address Line 1: PARK, VAUGHAN, FLEMING & DOWLER LLP
Address Line 2: 2820 FIFTH STREET
Address Line 4: DAVIS, CALIFORNIA 95618

ATTORNEY DOCKET NUMBER:	ORA13-0836
NAME OF SUBMITTER:	A. RICHARD PARK, REG. NO. 41,241
Signature:	/A. Richard Park/
Date:	02/06/2014

Total Attachments: 9
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CORPORATE ASSIGNMENT

WHEREAS, the undersigned,

Hiren D. Thacker	4185 Porte De Merano #154, San Diego, CA 92122
Frankie Y. Liu	401 Creekside Drive, Palo Alto, CA 94306
Robert David Hopkins, II	815 Sea Spray Lane, Unit 314, Foster City, CA 94404
Jon Lexau	8180 SW Miller Hill Road, Beaverton, OR 97007
Xuezhe Zheng	12442 Dormouse Road, San Diego, CA 92129
Guoliang Li	11341 Canter Heights Drive, San Diego, CA 92130
Ivan Shubin	15912 Camino Codorniz, San Diego, CA 92127
Ronald Ho	2761 Doverton Square, Mountain View, CA 94040
John E. Cunningham	12213 Carmel Vista Road, Apt. 233, San Diego, CA 92130
Ashok V. Krishnamoorthy	16132 Cayenne Creek Road, San Diego, CA 92127

hereinafter termed "Inventor(s)", have invented certain new and useful improvements in

HYBRID-INTEGRATED PHOTONIC CHIP PACKAGE WITH AN INTERPOSER

and have executed a declaration or oath for an application for a United States patent disclosing and identifying the invention:

__ On the ____ day of ________________________, 20___;

Or

X Said application having Application Number 14/047,910 and filed on 07 October 2013; and

WHEREAS, Oracle International Corporation, a corporation of the State of California, having a place of business at 500 Oracle Parkway, Mail Stop 5OP7, Redwood City, CA 94065, (hereinafter termed "Assignee"), is desirous of acquiring the entire right, title and interest in and to said application and the invention disclosed therein, and in and to all embodiments of the invention, heretofore conceived, made or discovered jointly or severally by said Inventor(s) (all collectively hereinafter termed "said invention"), and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter termed "patents") thereon granted in the United States and foreign countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Inventor(s) to have been received in full from said Assignee:

1. Said Inventor(s) do hereby sell, assign, transfer and convey unto said Assignee the entire right, title and interest (a) in and to said application and said invention; (b) in and to all rights to apply for foreign patents on said invention pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all applications filed and any and all patents granted on said invention in the United States or any foreign country, including each and every application filed and each and every patent granted on any application which is a divisional, substitution, continuation, or continuation-in-part of any of said applications; and (d) in and to each and every reissue or extensions of any of said patents.

2. Said Inventor(s) hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest herein conveyed in the United States and foreign countries. Such cooperation by said Inventor(s) shall include prompt production of pertinent

facts and documents, giving of testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said invention; (d) for filing and prosecuting applications for reissuance of any said patents; (e) for interference or other priority proceedings involving said invention; and (f) for legal proceedings involving said invention and any applications therefor and any patents granted thereon, including without limitation reissues and reexaminations, opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Inventor(s) in providing such cooperation shall be paid for by said Assignee.

3. The terms and covenants of this assignment shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Inventor(s), their respective heirs, legal representatives and assigns.

4. Said Inventor(s) hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, said Inventor(s) have executed and delivered this instrument to said Assignee as of the dates written below.

10/07/2013

Hiren D. Thacker Date

Frankie Y. Liu Date

Robert David Hopkins, II Date

Jon Lexau Date

Xuezhe Zheng 10/07/2013

Xuezhe Zheng Date

Guoliang Li Date

10/07/2013

Ivan Shubin Date

Ronald Ho Date

John E Cunningham 10/07/2013

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Ashok V. Krishnamoorthy Date

Attorney Docket No. ORA13-0836

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